

IN THE SPECIFICATION:

Please amend the specification as follows:

Please amend the paragraph beginning at page 1, line 25, and ending on page 2, line 6, as follows.

-- As a means for enabling adaptation to the F<sub>2</sub> laser, a method of sealing a space where exposure light passes with a ~~partition~~ partition, or the ~~like~~ like, and filling this space with an inert gas such as nitrogen may be possible. This system, however, also requires an inert gas temperature adjusting system and a circulating system for setting the temperature of the space ~~where~~ in which a wafer and reticle are arranged at a constant temperature and for removing temperature fluctuation. --

Please amend the paragraph beginning at page 3, line 20, as follows.

-- The conventional inert gas circulating system has the following problems in the case of periodical maintenance such as cleaning a wafer chuck arranged in the sealed space, or [[a]] trouble such as a wafer lost. --

Please amend the paragraph beginning at page 4, line 6, as follows.

-- (3) When a gas containing [[a]] moisture passes through the cooler, condensation occurs. The condensed water adversely influences circulation of the inert gas. --

Please amend the paragraph beginning at page 6, line 6, as follows.

-- A third aspect of the present invention is related to a device manufacturing method, forming a pattern onto a substrate by using an exposure apparatus according to ~~claim 6~~ the present invention. --

Please amend the paragraph beginning at page 7, line 23, and ending on page 8, line 6, as follows.

-- During maintenance, or the like, the gas of the external atmosphere such as the air can be introduced into the chamber 23. For example, the gas of the external atmosphere can be introduced to the chamber 23 through an external gas path. The external path can be formed by forming an opening in the chamber 23 and connecting a pipe to the opening. A suction valve 9 is connected to the external gas path. When introducing the gas of the external atmosphere into the chamber 23, both the shut-off valves 5 and 8 are closed and the suction valve 9 is opened. --

Please amend the paragraph beginning at page 8, line 7, as follows.

-- The temperature adjusting system has a supply unit for supplying a predetermined gas (e.g., inert gas) to the chamber 23, so that it can supply the predetermined gas to the chamber 23. In the temperature adjusting system, even if external air enters the chamber 23 filled with the predetermined gas by leakage, or the like, when both the shut-off valves 5 and 8 are closed, a gas containing [[a]] moisture will not be condensed by the cooler. --

Please amend the paragraph beginning at page 8, line 16, as follows.

-- With the above arrangement, in the temperature adjusting system, even if the gas of the external atmosphere is introduced into the chamber, for example, a gas containing [[a]] moisture can be prevented from passing through the cooler to condense. --

Please amend the paragraph beginning at page 9, line 17, as follows.

-- The temperature adjustment system 1 has internal ~~equipments~~ equipment, i.e., a blower 34, a cooler 29, a filter box 4, and heaters 31 that are arranged in this order in the flowing direction of the gas flows in the circulating paths 2' and 3'. A shut-off valve 5 is arranged between the blower 34 and cooler 29. Furthermore, in the circulating paths 2' and 3', an exhaust valve 6 and exhaust path 7 are arranged upstream of the shut-off valve 5. A shut-off valve 8 is arranged downstream of a filter box 4. --

Please amend the paragraph beginning at page 12, line 22, and ending on page 13, line 14, as follows.

-- Fig. 4 is a flow chart of an overall semiconductor device manufacturing process using the exposure apparatus described above. In step 1 (circuit design), a semiconductor device circuit is designed. In step 2 (mask fabrication), a mask is fabricated based on the designed circuit pattern. In step 3 (wafer fabrication), a wafer is manufactured by using a material such as silicon. In step 4 (wafer process), called a pre-process, an actual circuit is formed on the wafer by lithography using the prepared mask and wafer. In step 5 (assembly), called a post-process, a

semiconductor chip is formed by using the wafer fabricated in step 4, and includes processes such as an assembly process (dicing and bonding) and a packaging process (chip encapsulation). In step 6 (inspection), inspection such as the operation confirmation test and durability test of the semiconductor device fabricated in step 5 are conducted. After these steps, the semiconductor device is completed, and shipped (step 7). --